

# METHOD AND APPARATUS FOR PROTECTING WIRING AND INTEGRATED CIRCUIT DEVICE

## CROSS-REFERENCES TO RELATED APPLICATIONS

5 [01] ~~NOT APPLICABLE~~

*delete*  
*INS* *>* *This application is a divisional application of U. S. Serial No. 10/216,600 which is now U. S. Patent No. 6,809,934.*

STATEMENT AS TO RIGHTS TO INVENTIONS MADE UNDER

FEDERALLY SPONSORED RESEARCH OR DEVELOPMENT

[02] NOT APPLICABLE

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REFERENCE TO A "SEQUENCE LISTING," A TABLE, OR A COMPUTER  
PROGRAM LISTING APPENDIX SUBMITTED ON A COMPACT DISK.

[03] NOT APPLICABLE

15 The following embodiments of the invention relate generally to integrated  
circuits. More particularly, these embodiments relate to micromachined (MEMS) devices.

## BACKGROUND

[04] In integrated circuits, it is common to provide various layers of material so as to  
fabricate the integrated circuit. This process is completed by depositing a passivation layer  
20 so as to protect the earlier deposited layers of materials. Furthermore, it is common to cap  
the integrated circuits with a plastic material to prevent their destruction. One type of  
integrated circuit, however, does not allow for such a passivation layer to be applied in view  
of the fact that the integrated circuit is comprised of an active mechanical component.

[05] For example, in the field of micromachined (MEMS) devices, it is common to provide  
25 an active mechanical component, such as a mirror, that needs to be exposed to the  
atmosphere. In the case of a MEMS device that is comprised of mirrors, the mirrors need to  
be capable of receiving light transmission signals so that these transmission signals can be  
properly routed by reflection from the mirrors. Similarly, other components, for example,  
allow refraction or diffraction of various optical signals. These are merely examples, as  
30 MEMS devices can be comprised of other active mechanical components. Such MEMS  
devices make packaging of the integrated circuit components difficult in view of the fact that